TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (兀MOS)

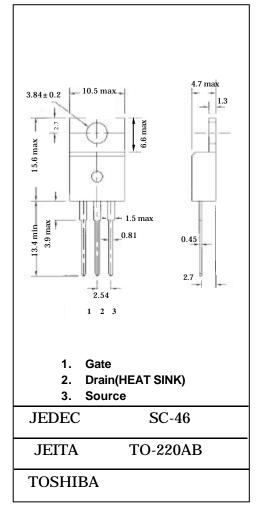
2SK3759

Switching Regulator Applications

- Low drain-source ON resistance: RDS (ON) = 0.75 (typ.)
- High forward transfer admittance: $|Y_{fs}| = 6.5S$ (typ.)
- Low leakage current: $I_{DSS} = 100 \ \mu A (V_{DS} = 500 \text{ V})$
- Enhancement-mode: $V_{th} = 2.0 \sim 4.0 V (V_{DS} = 10 V, I_D = 1 mA)$

Maximum Ratings (Ta = 25°C)

Characteristics		Symbol	Rating	Unit
Drain-source voltage		V _{DSS}	500	V
Drain-gate voltage ($R_{GS} = 20 \text{ k}\Omega$)		V _{DGR}	500	V
Gate-source voltage		V _{GSS}	±30	V
	DC (Note 1)	ΙD	8	
	Pulse (t = 1 ms) (Note 1)	I _{DP}	32	
Drain power dissipation (Tc = 25°C)		PD	74	W
Single pulse avalanche energy (Note 2)		E _{AS}	48	mJ
Avalanche current		I _{AR}	8	А
Repetitive avalanche energy (Note 3)		E _{AR}	7.4	mJ
Channel temperature		T _{ch}	150	°C
Storage temperature range		T _{stg}	-55~150	°C



Thermal Characteristics

Characteristics	Symbol	Max	Unit
Thermal resistance, channel to case	R _{th (ch-c)}	1.68	°C/W
Thermal resistance, channel to ambient	R _{th (ch-a)}	83.3	°C/W

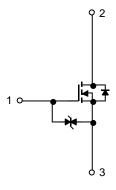
Weight : 2.0g(typ.)

Note 1: Please use devices on conditions that the channel temperature is below 150 °C.

Note 2: $V_{DD} = 90 \text{ V}, \text{ T}_{ch} = 25^{\circ}\text{C}(\text{initial}), \text{ L} = 1.28 \text{ mH}, \text{ I}_{AR} = 8 \text{ A}, \text{ R}_{G} = 25 \Omega$

Note 3: Repetitive rating: Pulse width limited by maximum channel temperature

This transistor is an electrostatic sensitive device. Please handle with caution.



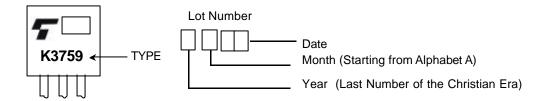
Electrical Characteristics (Ta = 25°C)

Chara	acteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage current		lgss	$V_{GS} = \pm 25 V, V_{DS} = 0 V$	_		±10	μΑ
Gate-source brea	akdown voltage	V (BR) GSS	$I_D = \pm 10 \ \mu A, \ V_{GS} = 0 \ V$	±30			V
Drain cut-off curr	ent	I _{DSS}	$V_{DS} = 500 \text{ V}, \text{ V}_{GS} = 0 \text{ V}$	_		100	μA
Drain-source bre	akdown voltage	V (BR) DSS	$I_D = 10 \text{ mA}, V_{GS} = 0 \text{ V}$	500		_	V
Gate threshold ve	oltage	V _{th}	$V_{DS} = 10 \text{ V}, \text{ I}_{D} = 1 \text{ mA}$	2.0		4.0	V
Drain-source ON	resistance	R _{DS (ON)}	$V_{GS} = 10 \text{ V}, \text{ I}_{D} = 4 \text{ A}$		0.75	0.85	Ω
Forward transfer	admittance	Y _{fs}	$V_{DS} = 10 V, I_{D} = 4 A$	3.0	6.5		S
Input capacitance		C _{iss}	$V_{DS} = 25 V, V_{GS} = 0 V, f = 1 MHz$	_	1050	_	pF
Reverse transfer capacitance		C _{rss}		_	10		
Output capacitance		Coss		_	110		
Switching time	Rise time	tr	$V_{GS} = 4 A V_{OUT}$ $V_{GS} = 50 \Omega$ $V_{DD} = 200 V$ $V_{DD} = 10 \mu s$	_	26	_	ns
	Turn-on time	t _{on}		_	45	_	
	Fall time	t _f			38		
	Turn-off time	t _{off}		_	130	_	
Total gate charge		Qg		_	28	_	
Gate-source charge		Q _{gs}	$V_{DD}{\simeq}400$ V, $V_{GS}{=}10$ V, $I_{D}{=}8$ A		16		nC
Gate-drain charge		Q _{gd}			12		

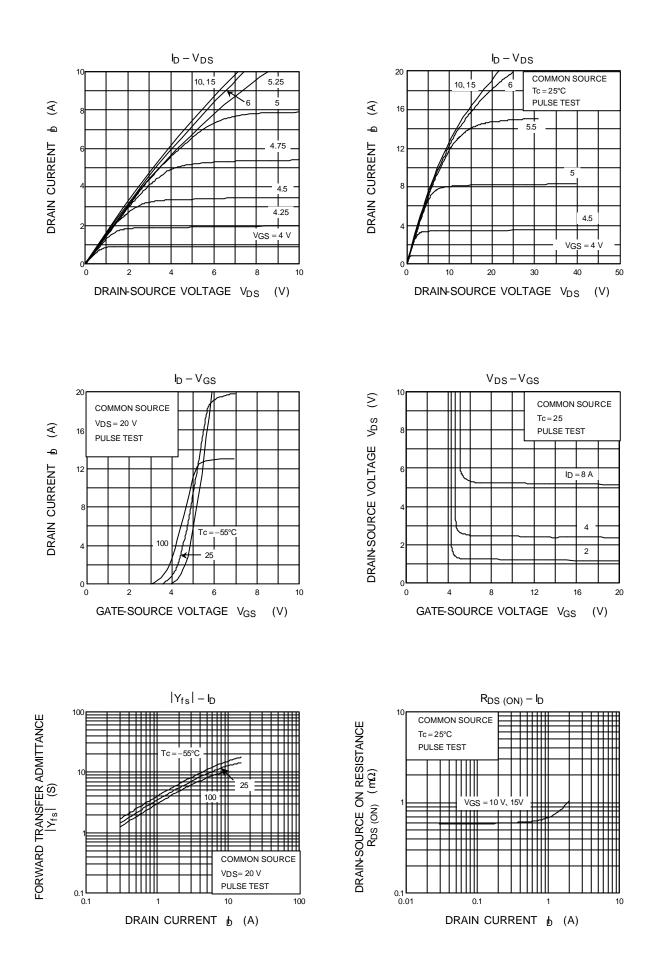
Source-Drain Ratings and Characteristics (Ta = 25°C)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current (Note 1)	I _{DR}	—		_	8	А
Pulse drain reverse current (Note 1)	I DRP	_	_	_	32	А
Forward voltage (diode)	V _{DSF}	$I_{DR} = 8 \text{ A}, V_{GS} = 0 \text{ V}$		_	-1.7	V
Reverse recovery time	t _{rr}	$I_{DR} = 8 \text{ A}, V_{GS} = 0 \text{ V},$	_	1200	_	ns
Reverse recovery charge	Q _{rr}	dl _{DR} /dt = 100 A/µs		10		μC

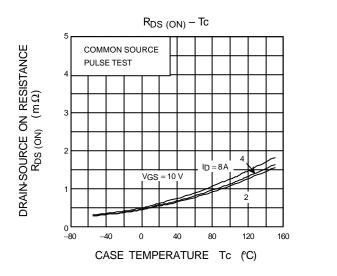
Marking

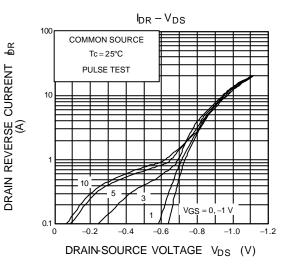


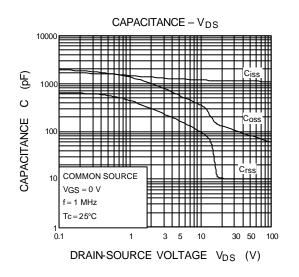
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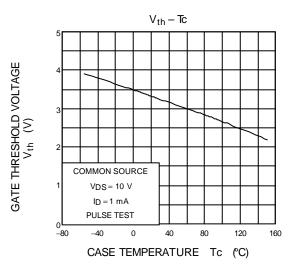


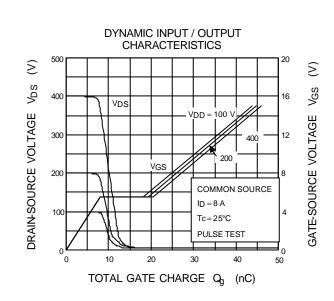
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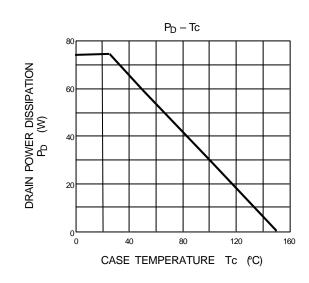


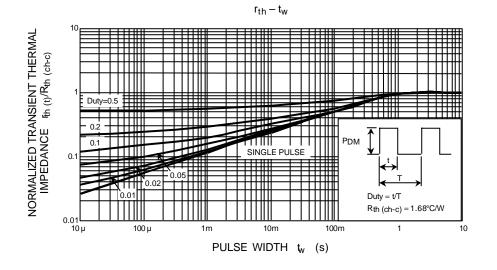


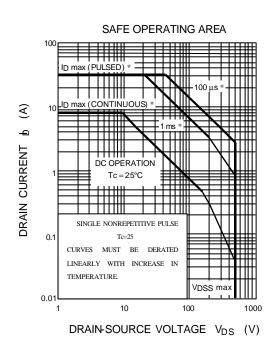


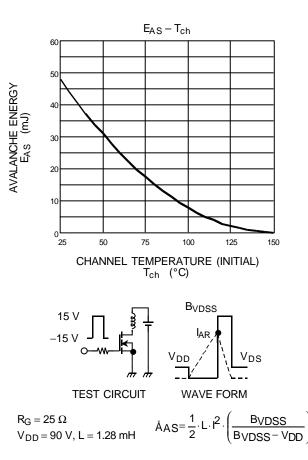












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